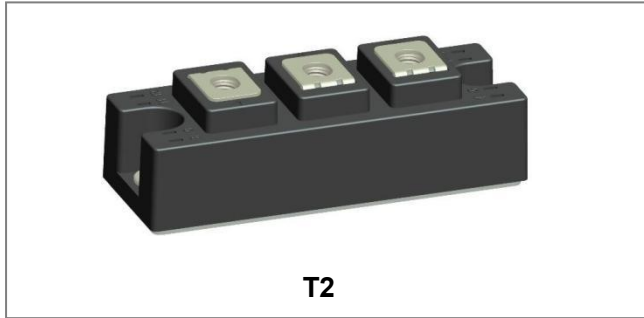


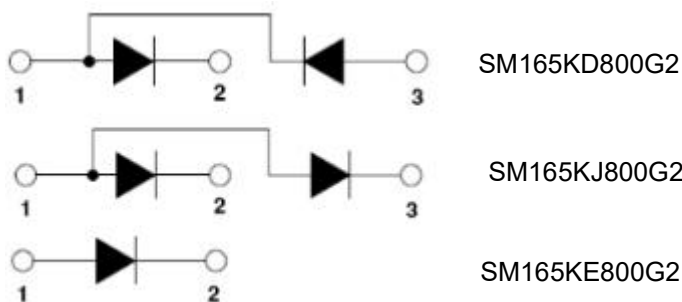
**SM165KD800G2 SM165KJ800G2 SM165KE800G2
SCHOTTKY RECTIFIER**



Features

- Heat transfer through aluminum oxide DBC
Ceramic isolated metal baseplate
- Industrial standard package
- Thick copper baseplate
- 2500 VRMS isolating voltage
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Power Supplies
- AC&DC Motor Drivers
- Bridge Circuits
- Welders
- Battery Supplier

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	-	800	V
State the average current	$I_{F(AV)}$	Single phase ,half wave 180°conduction $T_c=85^\circ\text{C}$	165	A
Surge forward current	I_{FSM}	$t=10\text{mS } T_J=45^\circ\text{C}$	6000	A
Maximum I^2t for fusing	I^2t	$t=10\text{mS } T_J=45^\circ\text{C}$	180000	A ² s

Electrical Characteristics:

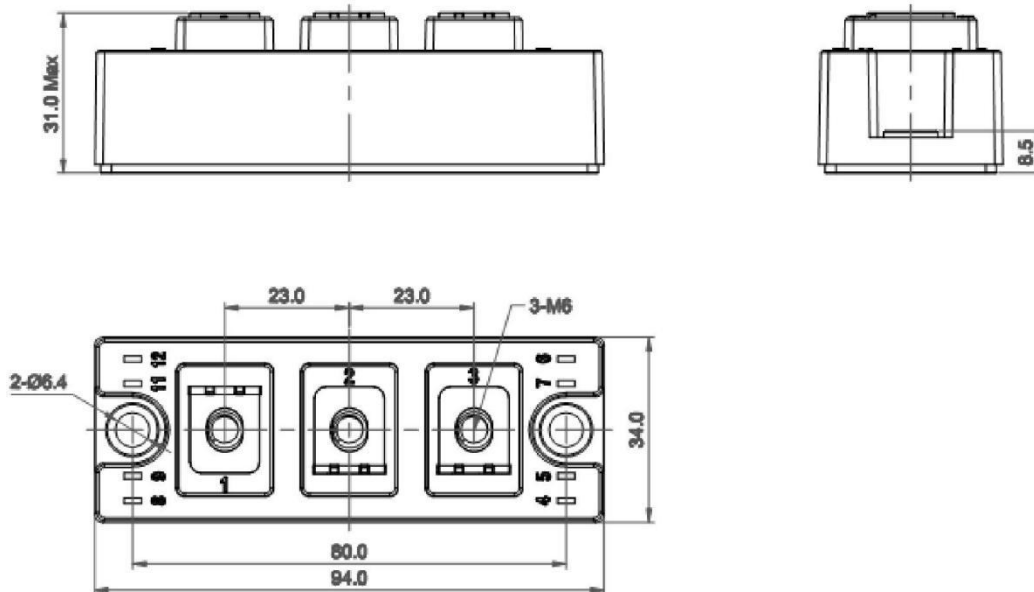
Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(per leg)*	V_{F1}	@ 165A, Pulse, $T_J = 25\text{ }^\circ\text{C}$	1.05	1.25	V
Reverse Current(per leg)*	I_{R1}	@ $V_R = \text{rated } V_R$ $T_J = 25\text{ }^\circ\text{C}$	-	20	μA
	I_{R2}	@ $V_R = \text{rated } V_R$ $T_J = 150\text{ }^\circ\text{C}$	-	5	mA
Isolation Breakdown Voltage(R.M.S)	Visol	Ac.50Hz; R.M.S; 1min	-	2500	V
		Ac.50Hz; R.M.S; 1sec	-	3500	

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-40~+150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-	-40~+150	$^\circ\text{C}$
Maximum internal thermal resistance, junction to case per leg	$R_{\text{th}(J-C)}$	Per diode	0.21	$^\circ\text{C/W}$
Typical thermal resistance, case to heatsink per module	$R_{\text{th}(C-S)}$	Module	0.05	$^\circ\text{C/W}$
Mounting Torque	M_t	To terminals(M6)	5 \pm 15%	Nm
	M_s	To heatsink(M6)	5 \pm 15%	
Module(Approximately)	Weight		160	g

Mechanical Dimensions T2 (Millimeters)



Ordering Information

Device	Package	Shipping
SM165KD800G2 SM165KJ800G2 SM165KE800G2	T2	10pcs/ box

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXX is YYWW

SM165KD800G2/SM165KJ800G2/SM165KE800G2 = Part name
SS = SS
YY = Year
WW = Week

Cautions: Molding resin
Epoxy resin UL:94V-0

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